AP&S
Customized Solutions

WE ARE THE PARTNER FOR CUSTOMIZED WET PROCESS EQUIPMENT

NID™ *Dry*

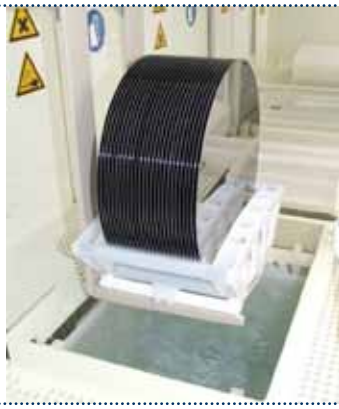
Drying technology for up to 300mm wafers

SEMI PARTS
An AP&S Business Unit

BENEFITS

NID *Dry* stands for Nitrogen IPA Dispense Dry and is a surface tension gradient dryer
Drying technology for up to 300 mm wafers.

- Stand-alone or integrated in a wet bench
- Optimized footprint
- Proven technology
- Watermark-free
- No wafer breakage



FEATURES & BENEFITS

Applications

Drying of wafers, ICs, MEMS, LED, photo masks, glas substrates

General Features

- Drying of 25 or 50-wafer batches up to 300 mm wafers
- Standard high or low profile cassettes

Specification

Process Time:	typical < 10 min, depending on selected recipe
Hydrophilic wafers:	≤ 10 adders @ 0.12 µm
Hydrophobic wafers:	≤ 30 adders @ 0.12 µm
Metal contamination:	≤ $1 \cdot 10^{10}$ atoms / cm^2 added for any trace metal
Drying spots:	non, after drying
IPA consumtion:	≤ 30 ml / run
Edge exclusion:	3 mm

Graphical User Interface

- Based on B&R plc
- Recipe editor
- Automatic generation of diagnostic files (EOR, ERR etc.)
- Multi-tiered password levels

General Installation data

Dimensions:	660 x 1440 x 2200 (L x D x H)
Nom. Voltage:	3 x 400 VAC
Rated frequency:	50 Hz
Nominal current:	3 x 33 A (etc.)

Available training

Operator, maintenance and process

Build to comply with

- CE
- Semi S2 and S8
- FM 4910
- SECS/GEM

Available options

- Minienvironment
- IPA concentration monitoring system
- N2 hot
- UPS unit

Reliability

- MTBF ≥ 800 h
- MTBA ≥ 300 h
- Uptime ≥ 97 %

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